

Title (en)  
THERMALLY STABILIZED COMPOSITIONS

Title (de)  
THERMOSTABILISIERTE ZUSAMMENSETZUNGEN

Title (fr)  
COMPOSITIONS RENDUES STABLES À LA CHALEUR

Publication  
**EP 3652253 A1 20200520 (DE)**

Application  
**EP 18736957 A 20180712**

Priority  
• EP 17181102 A 20170713  
• EP 2018068995 W 20180712

Abstract (en)  
[origin: WO2019012061A1] The invention relates to thermally stabilized polyamide 66 based compositions which contain reinforcing materials and which are based on at least one partially aromatic polyamide, at least one copper halide and at least one polyhydric alcohol, thus produced moulding compounds and also thus produced injection moulded, blow moulded or extruded products.

IPC 8 full level  
**C08L 77/06** (2006.01); **B29C 45/00** (2006.01); **B29C 48/00** (2019.01); **C08K 3/00** (2018.01); **C08K 3/014** (2018.01)

CPC (source: EP KR US)  
**B29B 9/06** (2013.01 - US); **B29B 9/12** (2013.01 - US); **B29B 11/10** (2013.01 - KR); **B29C 45/0001** (2013.01 - KR US); **B29C 48/022** (2019.01 - US); **B29C 48/023** (2019.01 - KR); **B29C 48/05** (2019.01 - KR US); **B29C 49/0005** (2013.01 - KR US); **B29C 49/04** (2013.01 - KR); **C08K 3/013** (2017.12 - KR); **C08K 3/16** (2013.01 - EP KR); **C08K 5/053** (2013.01 - EP KR); **C08K 7/14** (2013.01 - EP KR); **C08L 77/06** (2013.01 - EP KR US); **F02B 77/11** (2013.01 - KR); **B29C 48/022** (2019.01 - EP); **B29K 2077/00** (2013.01 - US); **B29K 2077/10** (2013.01 - EP KR); **C08K 3/16** (2013.01 - US); **C08K 3/40** (2013.01 - US); **C08K 5/053** (2013.01 - US); **C08K 7/14** (2013.01 - US); **C08L 2205/025** (2013.01 - KR)

C-Set (source: EP)  
**C08L 77/06 + C08K 3/16 + C08K 5/053 + C08K 7/14 + C08L 77/06**

Citation (search report)  
See references of WO 2019012061A1

Cited by  
CN114517012A

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**WO 2019012061 A1 20190117**; CN 110832030 A 20200221; DE 202018006238 U1 20190925; EP 3652253 A1 20200520; JP 2020526648 A 20200831; KR 20200030529 A 20200320; US 2021079218 A1 20210318

DOCDB simple family (application)  
**EP 2018068995 W 20180712**; CN 201880044090 A 20180712; DE 202018006238 U 20180712; EP 18736957 A 20180712; JP 2020501277 A 20180712; KR 20207000516 A 20180712; US 201816630531 A 20180712